



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D

*\* : Required Field*

<b>Supplier Information</b>			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2020-01-15
<b>Company Unique ID</b>	NL 008751171B01		
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Contact Phone *</b>	Refer to Supplier Comment section	<b>Contact Email *</b>	Refer to Supplier Comment section
<b>Authorized Representative *</b>	Rossana Bonaccorso	<b>Representative Title</b>	ADG MD CHAMPION
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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**Legal Statement**

<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
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**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STGD25N36LZAG	XMDP*SZA4A62	A	3068	2020-01-15
	Amount	UoM	Unit type	ST ECOPACK Grade
	330	mg	Each	ECOPACK 1
Comment	ECOPACK® or ECOPACK® 1 is STMicroelectronics trade name for ROHS compliant devices			

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
Bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy	DM00652462	

Package Designator	Size	Nbr of instances	Shape	
SIP	6.50,6.10,2.30	3	gull wing	
Comment	TO 252 DPAK			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : ELV directive : 2000/53/EC amended 2017/2096 _November 2017	
Query	Response
1 - Product(s) meets EU ELV requirements without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
Exemption Id.	Description
8e	Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)

QueryList : California Prop65 list, dated 13th September 2019			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.18	Die - Leadframe	533
Lead	4.27	Soft solder	12930
Antimony trioxide	1.77	Mold compound	5364

QueryList : REACH-16th July 2019				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
Lead	1000 ppm	4.27	Soft solder	12930
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material
Lead	1000 ppm	4.27	Soft solder	955013

Material Composition Declaration :						Mfr Item Name	XMDP*SZA4A62					
note : Substance present with less 0.001mg will not be declared in this document												
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	11.261	mg	supplier	die	Silicon(Si)	7440-21-3		10.859	mg	964302	32906
				supplier	metallisation	Aluminium(Al)	7429-90-5		0.151	mg	13409	458
				supplier	metallisation	Chromium(Cr)	7440-47-3		0.006	mg	533	18
				supplier	metallisation	Nickel(Ni)	7440-02-0		0.052	mg	4618	158
				supplier	metallisation	Silver(Ag)	7440-22-4		0.018	mg	1598	55
				supplier	Passivation	Silicon nitride(SiN)	12033-89-5		0.036	mg	3197	109
				supplier	passivation	Silicon oxide	7631-86-9		0.053	mg	4706	161
				supplier	polymer coating	Durimide	proprietary		0.086	mg	7637	261
				Leadframe	M-004 Copper and its alloys	165.099	mg	supplier	alloy & coating	Copper(Cu)	7440-50-8	
supplier	alloy & coating	Nickel(Ni)	7440-02-0						0.124	mg	751	376
supplier	alloy & coating	Iron(Fe)	7439-89-6						0.076	mg	460	230
supplier	alloy & coating	Iron Phosphide(FeP)	26508-33-8						0.139	mg	842	421
supplier	alloy & coating	Phosphorus metal	7723-14-0						0.012	mg	73	36
Soft solder	Solder	4.468	mg	SVHC	solder	Lead(Pb)	7439-92-1	7a-Lead in high melting temper	4.267	mg	955013	12930
				supplier	solder	Silver(Ag)	7440-22-4		0.112	mg	25067	339
				supplier	solder	Tin(Sn)	7440-31-5		0.089	mg	19920	270
Bonding wires	M-003 Aluminum and its alloys	0.739	mg	supplier	wire	Aluminium (Al)	7429-90-5		0.739	mg	1000000	2239
Bonding wires 2	M-003 Aluminum and its alloys	0.088	mg	supplier	wire	Aluminium (Al)	7429-90-5		0.088	mg	1000000	267
Encapsulation	M-011 Other inorganic materials	147.301	mg	supplier	mold compound	Silica vitreous	60676-86-0		121.228	mg	822995	367358
				supplier	mold compound	Epoxy Cresol Novolac	29690-82-2		10.311	mg	70000	31245
				supplier	mold compound	Phenol resin	9003-35-4		5.892	mg	40000	17855
				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		4.419	mg	30000	13391
				supplier	mold compound	Antimony trioxide	1309-64-4		1.768	mg	12003	5358
				supplier	mold compound	Brominated epoxy resin	40039-93-8		2.946	mg	20000	8927
				supplier	mold compound	Carbon black	1333-86-4		0.737	mg	5002	2230
Connections coating	Solder	1.044	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		1.044	mg	1000000	3166